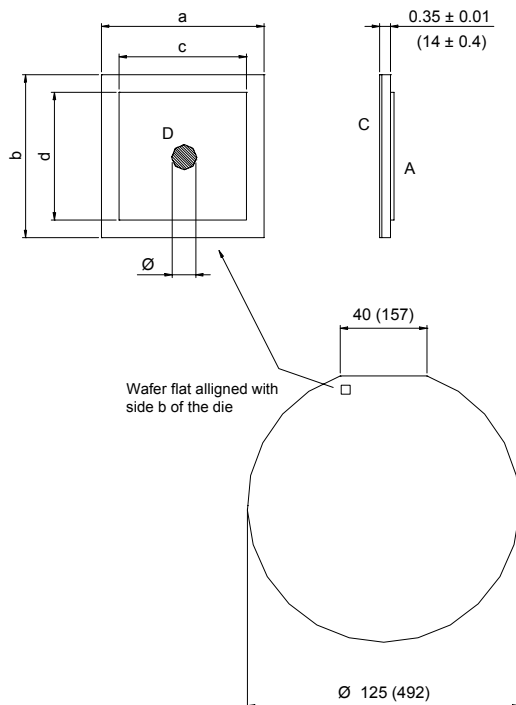


International
IOR Rectifier

SC050.....5. Series

SCHOTTKY DIE 50 x 50 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).

2. CONTROLLING DIMENSION: (MILS).

3. DIMENSIONS AND TOLERANCES:

$a = 1.27 + 0, - 0.01$

$(50 + 0, - 0.4)$

$b = 1.27 + 0, - 0.01$

$(50 + 0, - 0.4)$

$c = 1.12 + 0, - 0.01$

$(44 + 0, - 0.4)$

$d = 1.12 + 0, - 0.01$

$(44 + 0, - 0.4)$

$\varnothing = 0.7 \pm 0.1$

(30 ± 4)

4. LETTER DESIGNATION:

A = Anode (Top Metal)

C = Cathode (Back Metal)

D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

Recommended Blade

SEMITEC S1025 QS00 Blade

Sawing Street

$0.05 + 0, - 0.005$

$(2 + 0, - 0.2)$

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
 Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC050R015x5x	125	15	n.a. contact factory			
SC050S020x5x	150	20	n.a. contact factory			
SC050S030x5x	150	30	30	12	0.47 @ 2A	SMB
SC050S045x5x	150	45	15	8	0.55 @ 2A	DO-41
SC050S060x5x	150	60	20	6	0.60 @ 2A	SMA
SC050H045x5x	175	45	n.a. contact factory			
SC050H100x5x	175	100	n.a. contact factory			
SC050H150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC050xxxxA5x	Wire Bondable	—	Al 30 kÅ	—	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC050xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC050xxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	6300
SC050xxxx5R	Probed Die in Tape & Reel	n. a.
SC050xxxx5P	Probed Die in Waffle Pack	6300
SC050xxxx5F	Inked Probed Sawn Wafer on Film	6300

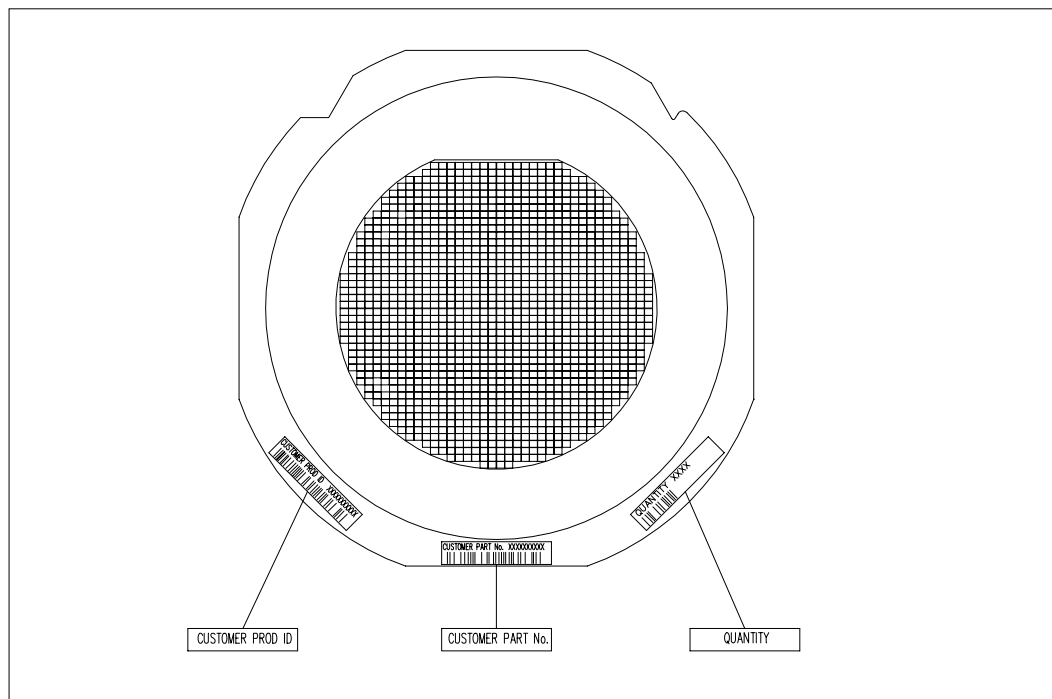
Ordering Information Table

Device Code						
1	2	3	4	5	6	7
SC	050	H	150	A	5	B

1	- Schottky Die
2	- Chip Dimension in Mils
3	- Process (see Electrical Characteristics Table)
4	- Voltage code: Code = V_{RRM}
5	- Chip surface metallization (see Mechanical Data Table)
6	- Wafer Diameter in inches
7	- Packaging (see Packaging Table)

H = 830 Process
R = OR'ing Process
S = Standard Process

Wafer on Film

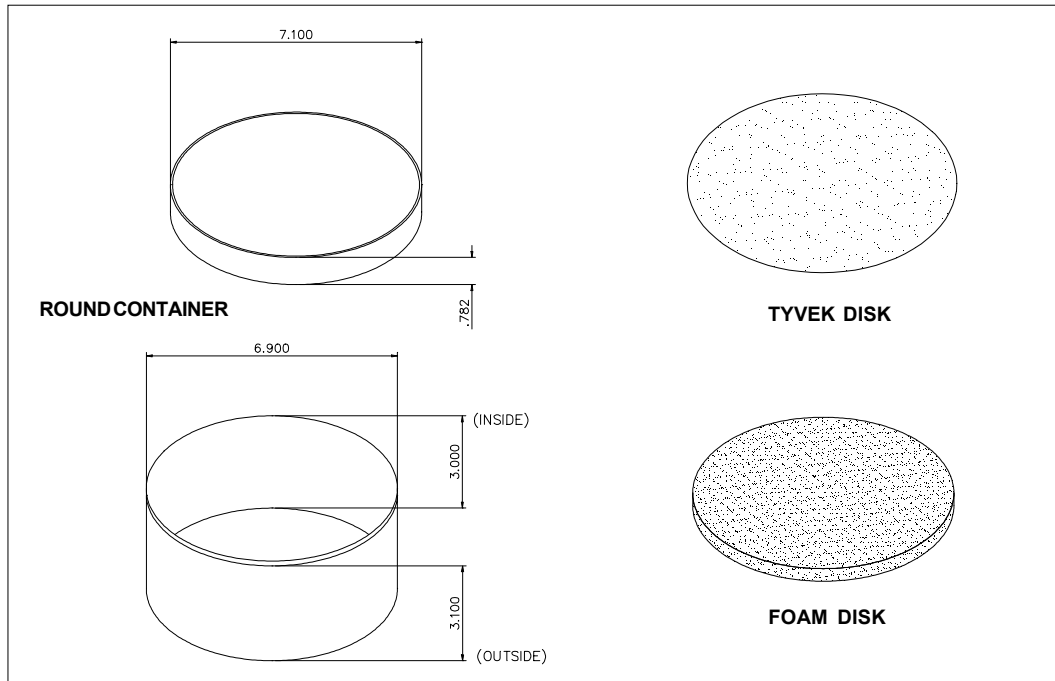


SC050.....5.

Bulletin I0510J rev. A 05/01

International
IOR Rectifier

Wafer in Box



Die in Waffle Pack

